

Feature

- ◇ High Speed Power Switching, logic level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free

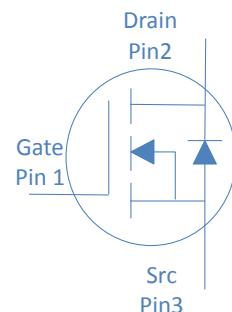
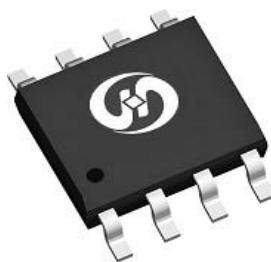
Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ Power Tools
- ◇ UPS
- ◇ Motor Control

Part Number	Package	Marking
HTS120N03	SOIC-8	TS120N03

30V N-Ch Power MOSFET

V_{DS}	30	V
$R_{DS(on),typ}$	$V_{GS}=10V$	9.7 mΩ
$R_{DS(on),typ}$	$V_{GS}=4.5V$	14.5 mΩ
I_D		12 A

SOIC-8

Absolute Maximum Ratings at $T_j=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_A=25^\circ C$	12	A
		$T_A=100^\circ C$	10	
Drain to Source Voltage	V_{DS}	-	30	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	48	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.3mH, T_C=25^\circ C$	7.2	mJ
Power Dissipation	P_D	$T_A=25^\circ C$	3	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{\theta JC}$	25	°C/W
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	50	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250\mu\text{A}$	1	1.7	3	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=20\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=24\text{V}, T_j=125^\circ\text{C}$	-	-	25	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=12\text{A}$	-	9.7	11.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=10\text{A}$	-	14.5	18	
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=12\text{A}$	-	15	-	S
Gate Resistance	R_{G}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	2.0	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=15\text{V}, f=1\text{MHz}$	-	1060	-	pF
Output Capacitance	C_{oss}		-	190	-	
Reverse Transfer Capacitance	C_{rss}		-	145	-	
Total Gate Charge (10V)	$Q_g(10\text{V})$	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=10\text{V}$	-	12	-	nC
Total Gate Charge (4.5V)	$Q_g(4.5\text{V})$			4.5		
Gate to Source Charge	Q_{gs}		-	1.2	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	3.7	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=1\text{A}, V_{\text{GS}}=10\text{V}, R_{\text{G}}=2.7\Omega,$	-	8	-	ns
Rise time	t_r		-	6	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	24	-	
Fall Time	t_f		-	3	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{F}}=2.5\text{A}$	-		1.2	V
Reverse Recovery Time	t_{rr}	$I_{\text{F}}=2.5\text{A}, dI_{\text{F}}/dt=100\text{A}/\mu\text{s}$	-	18	-	ns
Reverse Recovery Charge	Q_{rr}		-	10	-	nC

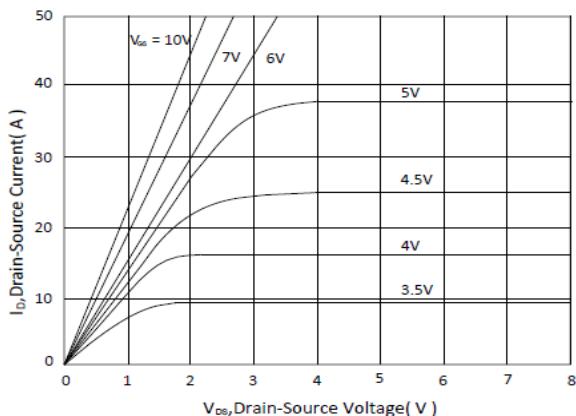
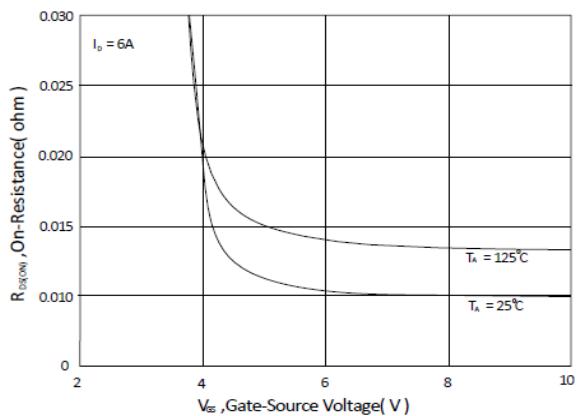
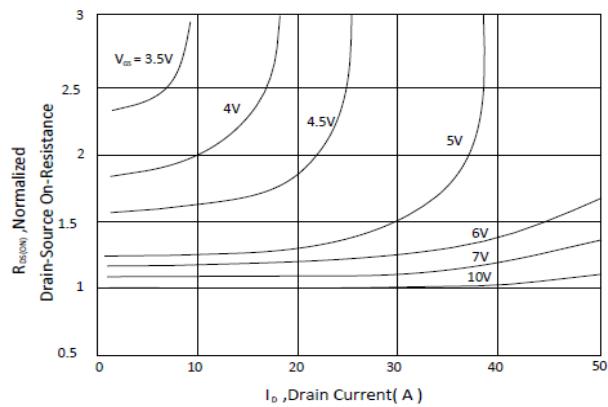
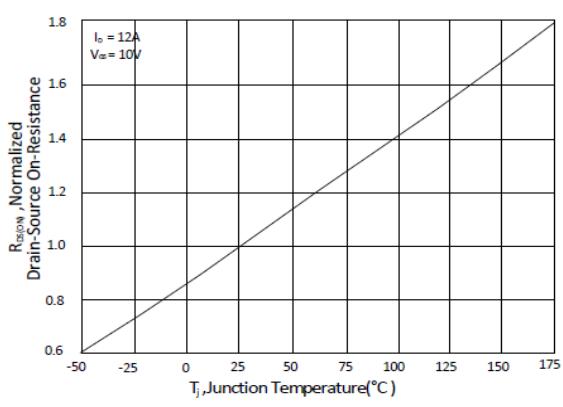
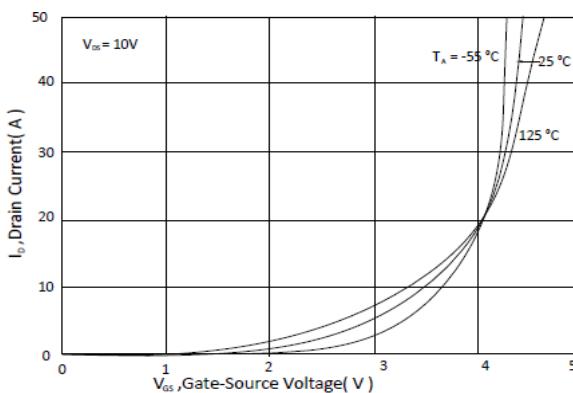
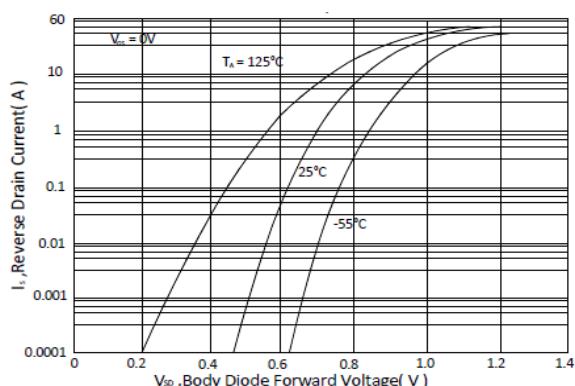
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

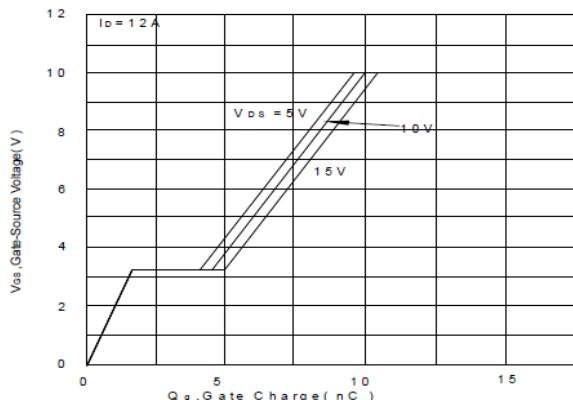


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

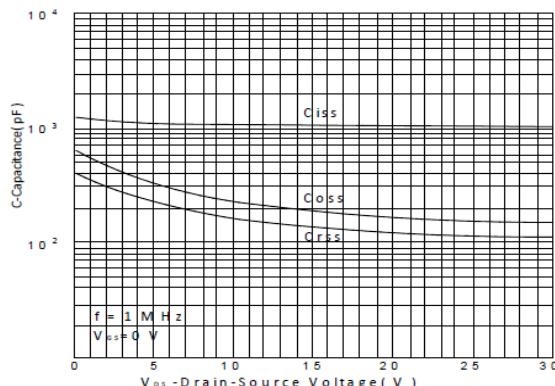


Figure 9. Maximum Safe Operating Area

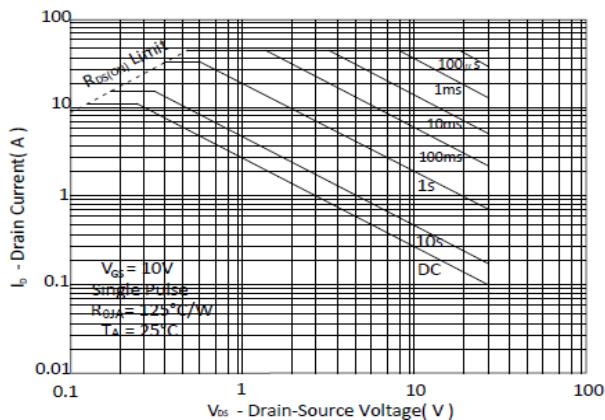


Figure 10. Single Pulse Maximum Power Dissipation

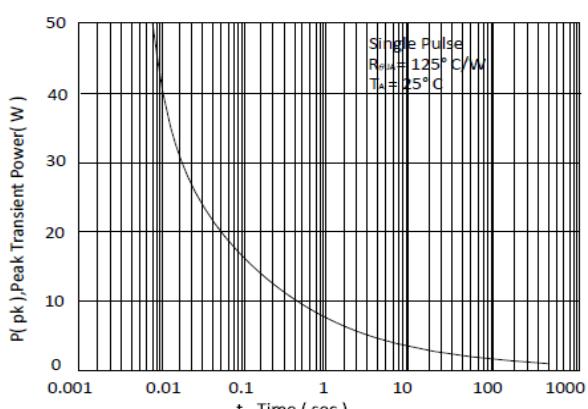
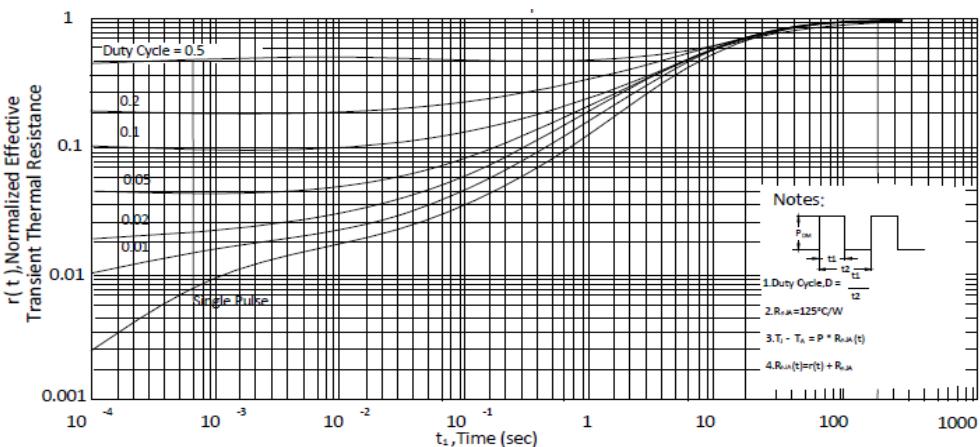
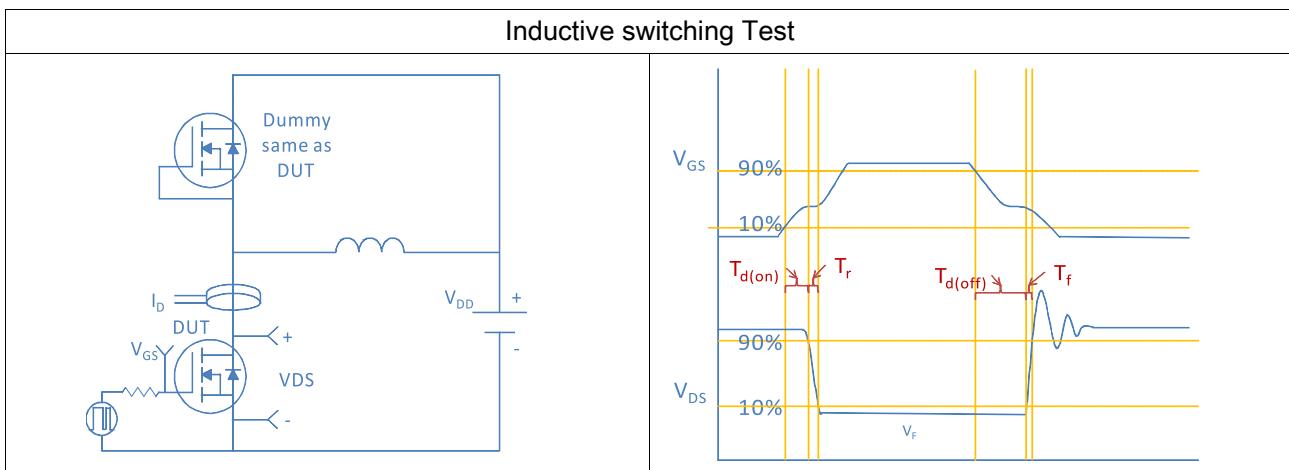
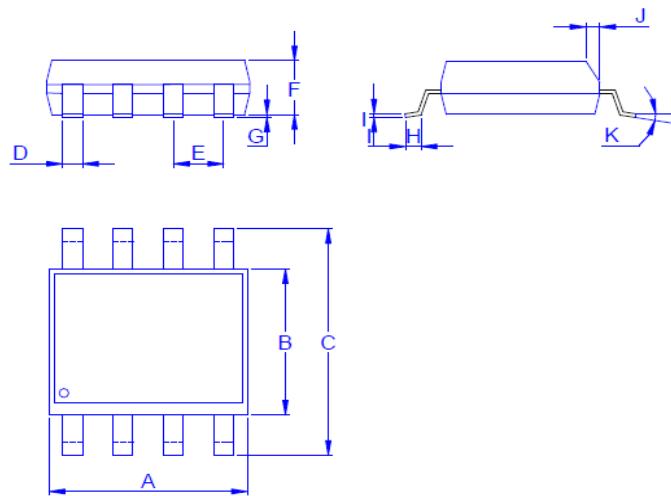


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case





SOIC-8, 8 leads



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°